



Power MOSFETS

DATASHEET

LM60350NAQ8A

N-Channel
Enhancement Mode MOSFET

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Quality Management Systems
ISO 9001:2015 Certificate

N-Channel Enhancement Mode MOSFET

Pin Description

SOP-8L(TOP view)	Symbol	Symbol	N-Channel	Unit
		V_{DSS}	60	V
		$R_{DS(ON)-Max}$	39	$m\Omega$
		ID	4.5	A

Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Applications

- Portable Equipment
- Battery Powered System

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM60350NAQ8A	SOP-8L	Tape & Reel	3000 / Tape & Reel	60350 <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/> <input type="checkbox"/>

Note : = Lot Code

Absolute Maximum Ratings ($T_J=25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter		N-Channel	Unit
V_{DSS}	Drain-Source Voltage	$T_A=25^\circ C$	60	V
V_{GSS}	Gate-Source Voltage		± 20	
T_J	Maximum Junction Temperature		150	$^\circ C$
T_{STG}	Storage Temperature Range		-55 to 150	$^\circ C$
$I_{DM}^{①}$	Pulse Drain Current Tested	$T_A=25^\circ C$	11	A
I_D	Continuous Drain Current	$T_A=25^\circ C$	4.5	A
		$T_A=70^\circ C$	3.6	
P_D	Maximum Power Dissipation	$T_A=25^\circ C$	1.5	W
		$T_A=70^\circ C$	0.9	
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.1mH	11	A
$E_{AS}^{②}$	Avalanche Energy, Single pulse	L=0.1mH	6	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{θJA}^{③}$	Thermal Resistance-Junction to Ambient	t<=10s	43
		Steady State	85

Note ① : Max. current is limited by junction temperature.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150 °C

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
$\mathbf{BV_{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_{DS}=250\mu\text{A}$	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=48\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu\text{A}$	1.2	1.8	2.5	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	-	-	± 100	nA
$R_{DS(\text{ON})}^{\text{(4)}}$	Drain-Source On-state Resistance	$V_{GS}=10\text{V}, I_{DS}=6\text{A}$	-	33	39	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_{DS}=5.5\text{A}$	-	36	47	
g_{fs}	Forward Transconductance	$V_{DS}=5\text{V}, I_{DS}=3\text{A}$	-	10	-	S
Dynamic Characteristics ⁽⁵⁾						
R_G	Gate Resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V},$ Freq.=1MHz	-	3.8	-	Ω
C_{iss}	Input Capacitance	$V_{GS}=0\text{V},$ $V_{DS}=30\text{V},$ Freq.=1MHz	-	1108	-	pF
C_{oss}	Output Capacitance		-	60	-	
C_{rss}	Reverse Transfer Capacitance		-	43	-	
$t_{d(\text{ON})}$	Turn-on Delay Time	$V_{GS}=10\text{V}, V_{DS}=30\text{V},$ $I_D=1\text{A}, R_{GEN}=6\Omega$	-	6.2	-	nS
t_r	Turn-on Rise Time		-	22	-	
$t_{d(\text{OFF})}$	Turn-off Delay Time		-	45	-	
t_f	Turn-off Fall Time		-	21	-	
Q_g	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=30\text{V}$ $I_D=6\text{A}$	-	13.2	-	nC
Q_g	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=30\text{V},$ $I_D=6\text{A}$	-	26	-	
Q_{gs}	Gate-Source Charge		-	4	-	
Q_{gd}	Gate-Drain Charge		-	4.8	-	
Source-Drain Characteristics						
$V_{SD}^{\text{(4)}}$	Diode Forward Voltage	$I_{SD}=3\text{A}, V_{GS}=0\text{V}$	-	0.75	1.1	V
t_{rr}	Reverse Recovery Time	$I_F=3\text{A}, V_R=0\text{V}$	-	20	-	nS
Q_{rr}	Reverse Recovery Charge		-	16	-	nC

Note ⁽⁴⁾ : Pulse test (pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$).

Note ⁽⁵⁾ : Guaranteed by design, not subject to production testing.

N-Channel Typical Characteristics

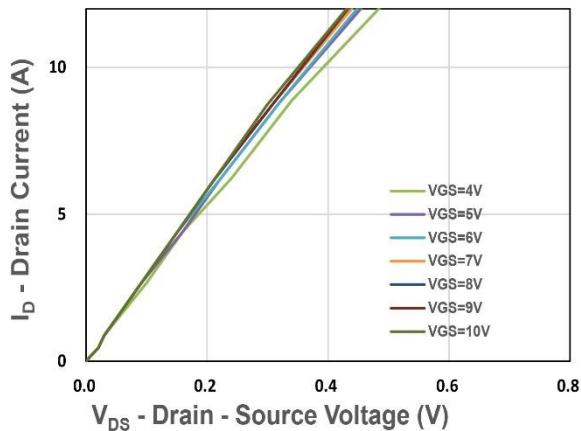


Figure 1. Output Characteristics

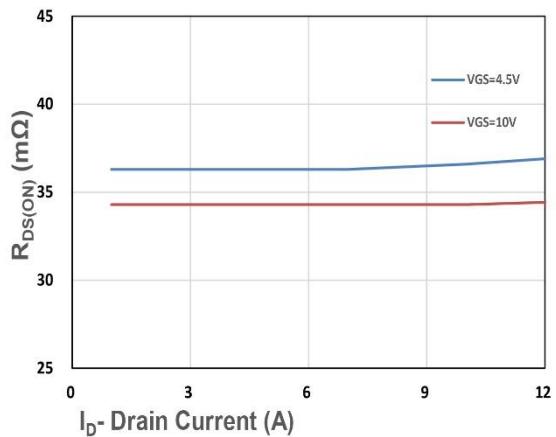


Figure 2. On-Resistance vs. ID

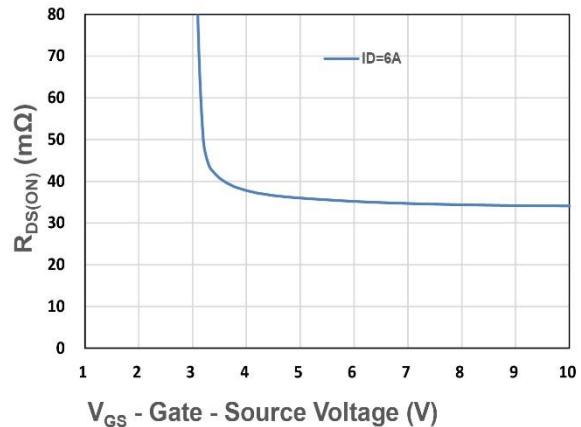


Figure 3. On-Resistance vs. VGS

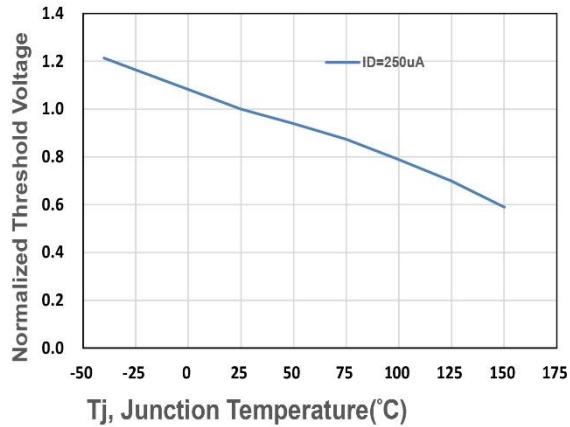


Figure 4. Gate Threshold Voltage

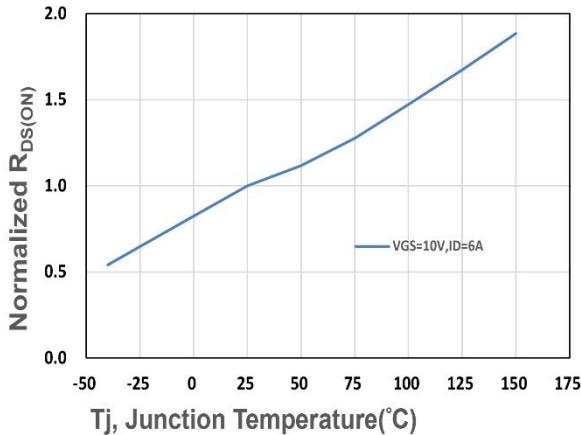


Figure 5. Drain-Source On Resistance

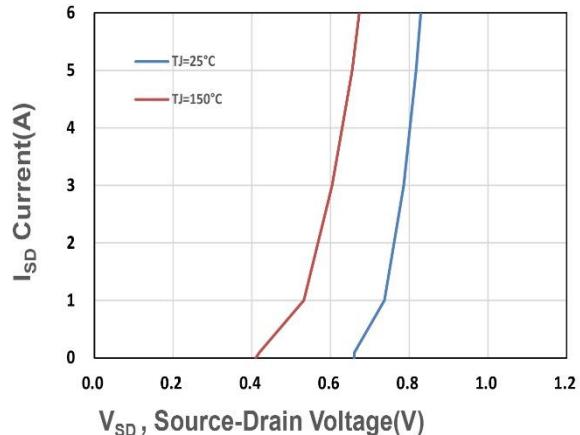


Figure 6. Source-Drain Diode Forward

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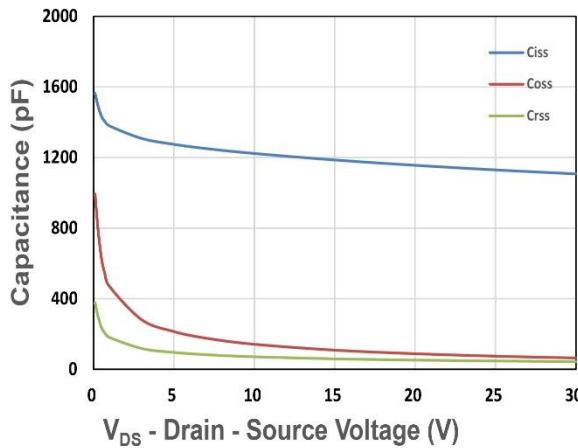


Figure 7. Capacitance

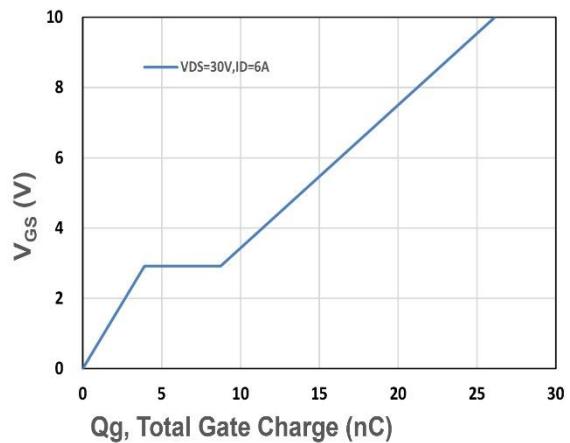


Figure 8. Gate Charge Characteristics

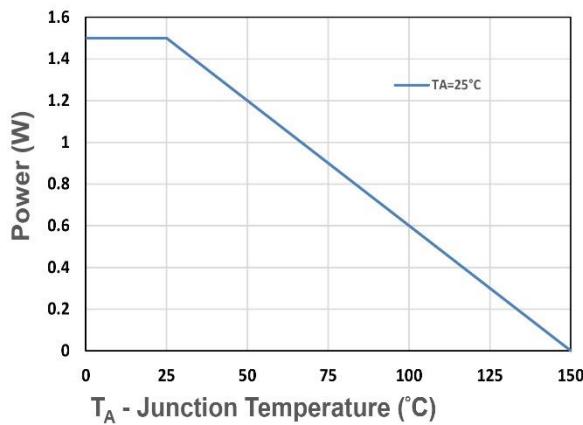


Figure 9. Power Dissipation

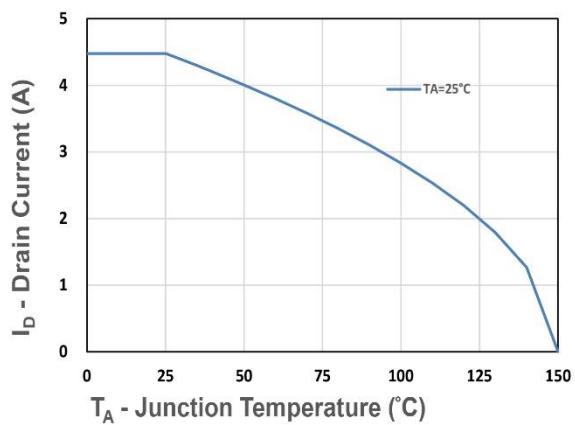


Figure 10. Drain Current

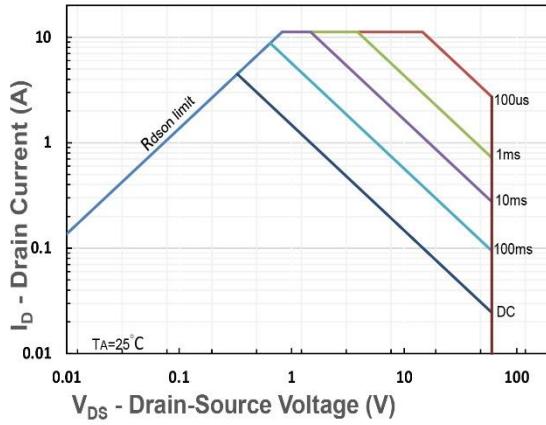


Figure 11. Safe Operating Area

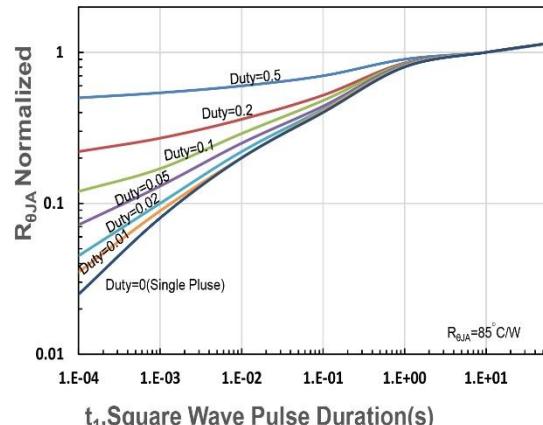


Figure 12. ReJA Transient Thermal Impedance